

10/593152

Date: September 18, 2006

APPLICATION DATA SHEET**Applicant Information**

Inventor One Given Name:: Seiji
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Name Suffix::
Postal Address Line One:: c/o Mitsui Mining & Smelting Co.,
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Division
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City:: Ageo-shi
State or Province:: Saitama
Country:: Japan
Postal or Zip Code 3620013
Citizenship Country:: Japan

Correspondence Information

Correspondence Customer Number:: 06449

Application Information

Title Line One:: ELECTRODEPOSITED COPPER FOIL WITH CARRIER
Title Line Two:: FOIL ON WHICH A RESIN LAYER FOR FORMING
Title Line Three:: INSULATING LAYER IS FORMED, COPPER-CLAD
Title Line Four:: LAMINATE, PRINTED WIRING BOARD, METHOD FOR
Title Line Five:: MANUFACTURING MULTILAYER COPPER-CLAD
Title Line Six:: LAMINATE, AND METHOD FOR MANUFACTURING
Title Line Seven:: PRINTED WIRING BOARD
Total Drawing Sheets:: 13
Formal Drawings?:: New
Application Type:: Utility
Docket Number:: 3209-124

Secrecy Order in Parent Appl?:: No

Representative Information

Representative Customer Number:: The practitioners associated
Representative Customer Number:: with customer number 06449

Domestic Priority Information

This application is a:: 371 of
>Application One:: PCT/JP2005/004501
Filing Date:: March 15, 2005
Patent Number::

Foreign Priority Information

Foreign Application One:: JP2004-075235
Filing Date:: March 16, 2004
Country:: Japan
Priority Claimed:: Yes

Assignment Information

Assignee name:: Mitsui Mining & Smelting Co., Ltd.
Street of mailing address:: 11-1, Osaki 1-chome
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State or Province of
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